

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An online ~~entrusting~~-system for entrusting a semiconductor package order, comprising-comprises:

a management ~~manage~~ and control unit for ~~to~~ processing ~~process~~ a said semiconductor package order inputted by a user via an Internet interface ~~of internet~~, wherein said semiconductor package order includes a required information selected from the group consisting of at least one information of a substrate information, a die dimension information, a package type information, a thermal performance information, an amount of substrate layers layer information, numbers of input terminals terminal information, and output terminals terminal information, and terminal pitch information of a pitches between said input and output terminals about said semiconductor package;

a database electrically coupled to said management ~~manage~~ and control unit for storing ~~to~~ store said required information and a schedule information;

at least one analysis module a plurality of analysis modules electrically coupled to said management ~~manage~~ and control unit for generating to produce an at least one analysis result corresponding to about said required information; and

a reply means for sending ~~responding~~ said analysis result of said analysis module modules to said user.

2-9. (Cancelled)

10. (Currently Amended) The system of claim 1, wherein said schedule information includes—a progress information of about processing said semiconductor package order and a result information of for processing said semiconductor package order.

11. (Currently Amended) The system of claim 1, wherein said plurality of analysis module modules are is selected from the group consisting of at least one of a thermal analysis module, a circuit analysis module, a stress analysis module, a reliability analysis module, a material analysis module, and a substrate analysis module.

12. (Currently Amended) An online method for entrusting a semiconductor package order, comprising: automatically providing online package entrusting comprises:

inputting a required information about a semiconductor package by a user via an Internet interface internet, wherein said required information is selected from selected from the group consisting of at least one information of a substrate information, a die dimension information, a package type information, a thermal performance information, an amount of substrate layers layer information, numbers of input terminals terminal information, and output terminal information terminals, and terminal pitch information of said pitches between said input and output terminals about said semiconductor package;

storing said required information in a database;

generating at least one analysis result by at least one analysis module producing a plurality of analysis results by a plurality of analysis modules according to said required information of said semiconductor package order;

storing recording said analysis result results in said database; and
sending responding said analysis result results to said user by a reply means.

13-19. (Cancelled)

20. (Currently Amended) The method of claim 12, wherein said analysis module is plurality of analysis modules are selected from the group consisting at least one of a thermal analysis module, a circuit analysis module, a stress analysis module, a reliability analysis module, a material analysis module, and a substrate analysis module.